The INF Series of Aluminum Cross Cut Fin Fin BGA Heatsinks with Fans are high efficiency cooling products designed for BGA Chipsets.

These devices mount with EZ Snap™ Mounting Clips to provide optimum cooling for various package sizes. These off-the-shelf, high efficiency solutions are easy to install and require no special board modifications or complex assemblies.

**Features:**

* High efficiency aluminum cross-cut fin design provides low pressure-drop characteristics
* Constructed of Extruded Aluminium AL6063 for optimum heat transfer
* DC Fan for improved heat dissipation
* Designed specifically for BGAs and other surface mount packages
* EZ-Snap™ Mounting Clip is constructed of UL94-V0 Rated Nylon
* Use Clip Tool HS8063 to attach (or remove) heatsink directly to BGA Chip
* Finished with black anodize plating
* Clip & Thermal Pad Options are pre-assembled at the factory

**Mechanical Outline Drawing**

(See 2nd page for “LW” & “H” dimensional values)

**EZ Snap™ Mounting Clip**

CLIPS DIRECTLY TO BGA CHIP WITH HS8063 CLIP TOOL

See page 2 for fitting chip heights. Consult Factory for unique Chip Height Requirements.

Note 1: Chip Height Measurements exclude ball dimensions (0.4mm)
Note 2: Chip must have 0.4mm clearance above the board for clip to adhere properly
Note 3: Maintain Keep-Out Clearance of 2.5mm around chip for clip to adhere properly
INF Series
Active BGA Heatsinks

Passive BGA Cooler Products:

HS1800 Series:
21-45mm Plate Fin (Aluminum)
Ideal for Linear Air Flow

HS2000-060 Series:
21-45mm Round Pin (Aluminum)
Ideal for Omni Directional Air Flow

HS2000-080 Series:
21-45mm Round Pin (Aluminum)
Ideal for Omni Directional Air Flow

INM-PCU Series:
19-42.5mm Elliptical Fin (Aluminum)
Ideal for Linear Air Flow and where Multiple Heatsinks are utilized

INM-P Series:
27-42.5mm Round Pin (Aluminum)
Ideal for Omni-Directional Airflow

INM-W Series:
27-42.5mm Round Pin (Aluminum)
Ideal for Omni-Directional Airflow

Custom Design and Manufacturing Services:
Our experienced engineers and production specialists are dedicated to the design and manufacture of cooling solutions to match our customers specific thermal issues, quickly and cost-effectively.

Features of our services include:
* Free Engineering Consultation
* Complimentary Thermal Analysis (Computational Fluid Dynamics and Design Simulation/Modeling)
* Wide range of technologies including: Investment Casting; Die Casting; Precision Forging; Skived Fin; Extrusions; Stamped Fin; and Custom Machining
* Rapid Prototyping Services to deliver concept models in as little as 2-5 business days and working prototypes in 1-3 weeks

Contact Radian Heatsinks to discuss your specific requirement today.

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radiansales@radianheatsinks.com
www.radianheatsinks.com
www.radianstore.com

INF Series
Active BGA Heatsinks

Notes:
1) Add suffix "+T710" to designate Thermally Conductive Phase Change Pad (Chomerics Part # T710).
2) Mounting Clips are constructed of UL94-VO rated nylon material and black in color.
3) Thermal Data provided is for reference only. Actual Cooling Performance may vary by application.
4) Specifications are subject to change without notice.

* Contact Radian to discuss unique Heatsink, Clip and Interface requirements.